

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SHUO-HSIU HSU	12/12/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	FOXCONN INTERCONNECT TECHNOLOGY LIMITED
<b>Street Address:</b>	Floor 4, Willow House, Cricket Square, P O Box 2804
<b>City:</b>	Grand Cayman
<b>State/Country:</b>	CAYMAN ISLANDS
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15846126
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(408)919-8353
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<b>Email:</b>	joseph.chung@fit-foxconn.com,sou-proce7@foxconn.com,sou-proce7@fit-foxconn.com
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<b>ATTORNEY DOCKET NUMBER:</b>	US60454
<b>NAME OF SUBMITTER:</b>	WEI TE CHUNG
<b>SIGNATURE:</b>	/WEI TE CHUNG/
<b>DATE SIGNED:</b>	12/18/2017
<b>Total Attachments: 2</b>	
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source=US60454171216ASM#page2.tif	

**ASSIGNMENT**

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- 1. SHUO-HSIU HSU , residing at New Taipei, Taiwan
- 2. \_\_\_\_\_ , residing at \_\_\_\_\_
- 3. \_\_\_\_\_ , residing at \_\_\_\_\_
- 4. \_\_\_\_\_ , residing at \_\_\_\_\_
- 5. \_\_\_\_\_ , residing at \_\_\_\_\_
- 6. \_\_\_\_\_ , residing at \_\_\_\_\_
- 7. \_\_\_\_\_ , residing at \_\_\_\_\_
- 8. \_\_\_\_\_ , residing at \_\_\_\_\_

hereby sell(s), assign(s) and transfer(s) unto: **FOXCONN INTERCONNECT TECHNOLOGY LIMITED** having a principal place of business at **Floor 4, Willow House, Cricket Square, P O Box 2804, Grand Cayman KY1-1112 , Cayman Islands**, hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **ALIGNMENT STRUCTURES FOR CHIP MODULES** for which the undersigned

[ ] previously executed --- Ser. No. \_\_\_\_\_ and filing date of \_\_\_\_\_  
[ x ] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>Shuo-Hsiu Hsu</u> SHUO-HSIU HSU	<u>12/12/2017</u> Date
2.	_____	_____ Date
3.	_____	_____ Date
4.	_____	_____ Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date